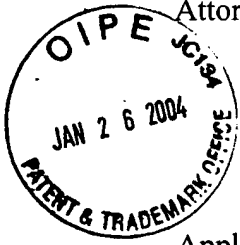


Application No.: 09/687,493  
Attorney Docket: AMKOR-045A



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants:	Sung Sik Jang	)	Confirmation No.	9392
		)		
Serial No.:	09/687,493	)	Art Unit:	2826
		)		
Filed:	10/13/2000	)	Examiner:	Williams,
		)		Alexander O.
For:	Semiconductor Package Having	)		
	Improved Adhesiveness and Ground	)		
	Bonding	)		

**AMENDMENT IN RESPONSE TO OFFICE ACTION**

Mail Stop Non-Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir/Madam:

In response to the Office Action mailed August 28, 2003 in relation to the above-identified patent application, please amend the application as follows:

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